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PRODUCT DISPLAY



PRODUCT DETAILS



Name: Solder paste

Model: BST-506B

Size: $\phi 37 \times 30$ mm

Weight: 50g

Composition: Sn63/Pb37

Melting point: 183°C



Storage: Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. New technical support, unique chemical formula provides excellent wettability, ensuring high reliability.

2. Use highly effective thixotropic agents to effectively prevent the collapse of printing and preheating, and ensure good printing and fine pattern.

3. More advanced thermal insulation technology, adhesive durability, not easy to dry, sticky time up to 48 hours.

4. High quality, unique formulation, perfect performance, easy to weld, bright and full of welding spot, no such phenomenon as false welding or false welding.

5. The residue is colorless and transparent. It does not affect the monitoring, cleaning and cleaning performance.

6. Good moisturizing and dry resistance. Under normal temperature, the shelf life is longer, which is suitable for mobile phone maintenance, computer digital maintenance industry, high precision circuit board SMT welding, BGA process welding, etc.

PRODUCT PHOTOGRAPH



